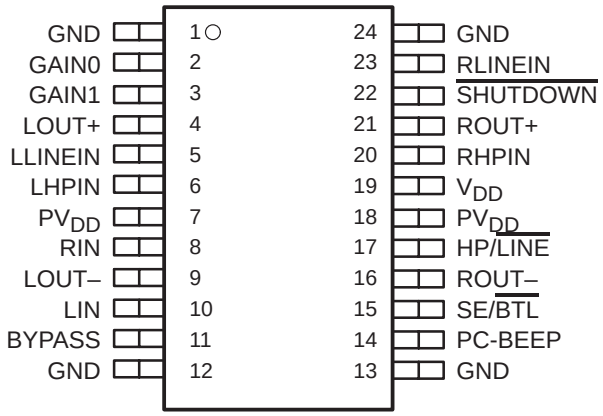
- **Compatible With PC 99 Desktop Line-Out Into 10-kΩ Load**
- **Compatible With PC 99 Portable Into 8-Ω Load**
- **Internal Gain Control, Which Eliminates External Gain-Setting Resistors**
- **2-W/Ch Output Power Into 3-Ω Load**
- **Input MUX Select Terminal**
- **PC-Beep Input**
- **Depop Circuitry**
- **Stereo Input MUX**
- **Fully Differential Input**
- **Low Supply Current and Shutdown Current**
- **Surface-Mount Power Packaging 24-Pin TSSOP PowerPAD™**

PWP PACKAGE
(TOP VIEW)



description

The TPA0222 is a stereo audio power amplifier in a 24-pin TSSOP thermally enhanced package capable of delivering 2 W of continuous RMS power per channel into 3-Ω loads. This device minimizes the number of external components needed, simplifying the design, and freeing up board space for other features. When driving 1 W into 8-Ω speakers, the TPA0222 has less than 0.5% THD+N across its specified frequency range.

Included within this device is integrated depop circuitry that virtually eliminates transients that cause noise in the speakers.

Amplifier gain is internally configured and controlled by two terminals (GAIN0 and GAIN1). BTL gain settings of 2, 6, 12, and 24 V/V are provided, while SE gain is always configured as 1 V/V for headphone drive. An internal input MUX allows two sets of stereo inputs to the amplifier. The HP/$\overline{\text{LINE}}$ terminal allows the user to select which MUX input is active regardless of whether the amplifier is in SE or BTL mode. In notebook applications, where internal speakers are driven as BTL and the line outputs (often headphone drive) are required to be SE, the TPA0222 automatically switches into SE mode when the SE/$\overline{\text{BTL}}$ input is activated, and reduces the gain to 1 V/V.

The TPA0222 consumes only 18 mA of supply current during normal operation. A miserly shutdown mode reduces the supply current to less than 150 μA.

The PowerPAD package (PWP) delivers a level of thermal performance that was previously achievable only in TO-220-type packages. Thermal impedances of approximately 35°C/W are truly realized in multilayer PCB applications. This allows the TPA0222 to operate at full power into 8-Ω loads at an ambient temperature of 85°C.

AVAILABLE OPTIONS

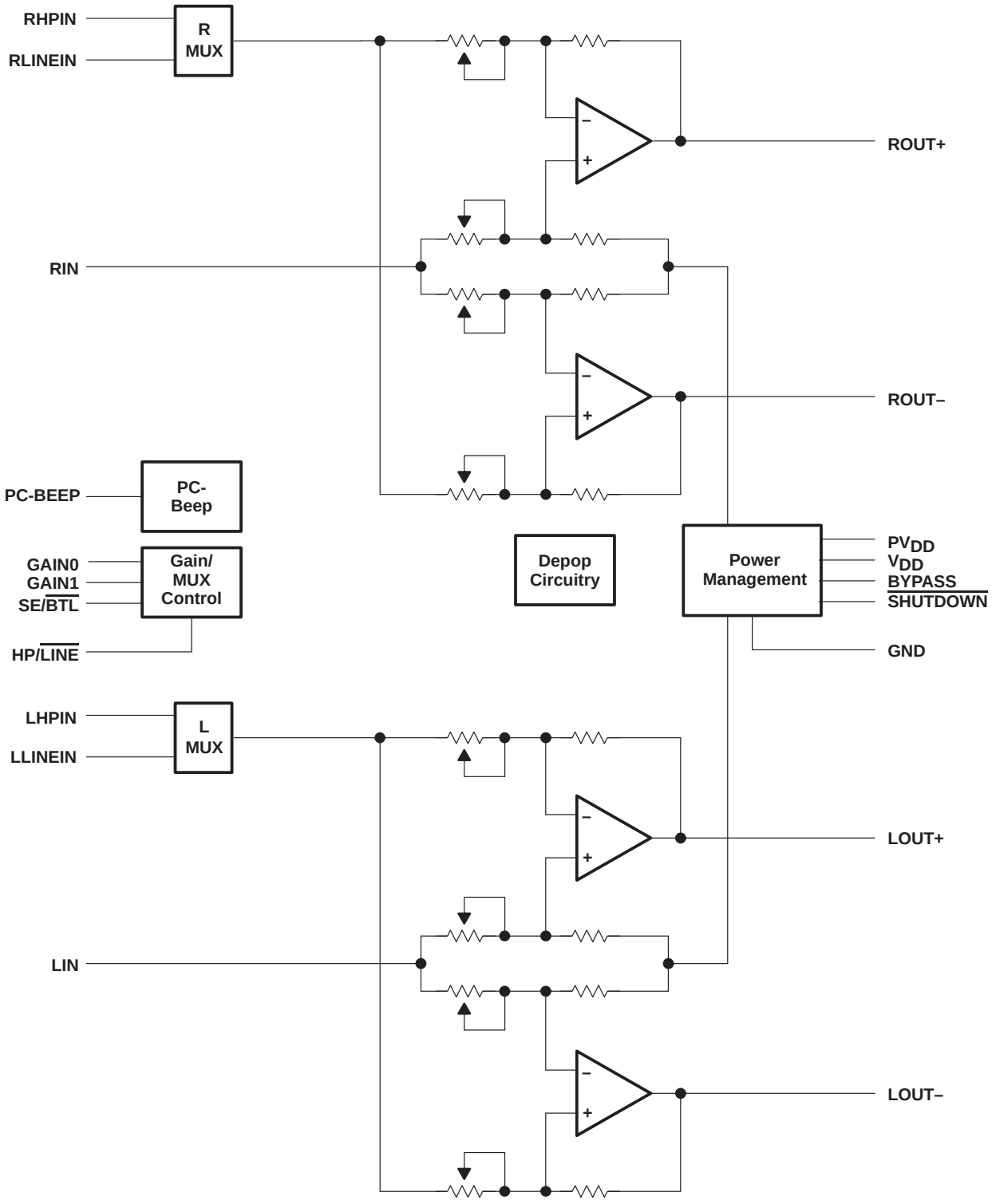
T_A	PACKAGED DEVICE
	TSSOP† (PWP)
–40°C to 85°C	TPA0222PWP

† The PWP package is available taped and reeled. To order a taped and reeled part, add the suffix R to the part number (e.g., TPA0222PWPR).

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments.

functional block diagram



Terminal Functions

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
BYPASS	11		Tap to voltage divider for internal mid-supply bias generator
GAIN0	2	I	Bit 0 of gain control
GAIN1	3	I	Bit 1 of gain control
GND	1, 12, 13, 24		Ground connection for circuitry. Connected to the thermal pad
LHPIN	6	I	Left channel headphone input, selected when SE/$\overline{\text{BTL}}$ is held high
LIN	10	I	Common left input for fully differential input. AC ground for single-ended inputs
LLINEIN	5	I	Left channel line input, selected when SE/$\overline{\text{BTL}}$ is held low
LOUT+	4	O	Left channel positive output in BTL mode and positive output in SE mode
LOUT–	9	O	Left channel negative output in BTL mode and high-impedance in SE mode
PC-BEEP	14	I	The input for PC-Beep mode. PC-BEEP is enabled when a > 1-V (peak-to-peak) square wave is input to PC-BEEP or PCB ENABLE is high.
HP/$\overline{\text{LINE}}$	17	I	HP/$\overline{\text{LINE}}$ is the input MUX control input. When the HP/$\overline{\text{LINE}}$ terminal is held high, the headphone inputs (LHPIN or RHPIN [6, 20]) are active. When the HP/$\overline{\text{LINE}}$ terminal is held low, the line BTL inputs (LLINEIN or RLINEIN [5, 23]) are active.
PV_{DD}	7, 18	I	Power supply for output stage
RHPIN	20	I	Right channel headphone input, selected when SE/$\overline{\text{BTL}}$ is held high
RIN	8	I	Common right input for fully differential input. AC ground for single-ended inputs
RLINEIN	23	I	Right channel line input, selected when SE/$\overline{\text{BTL}}$ is held low
ROUT+	21	O	Right channel positive output in BTL mode and positive output in SE mode
ROUT–	16	O	Right channel negative output in BTL mode and high-impedance in SE mode
$\overline{\text{SHUTDOWN}}$	22	I	Places entire IC in shutdown mode when held low, except PC-BEEP remains active
SE/$\overline{\text{BTL}}$	15	I	Hold SE/$\overline{\text{BTL}}$ low for BTL mode and hold high for SE mode.
V_{DD}	19	I	Analog V_{DD} input supply. This terminal needs to be isolated from PV_{DD} to achieve highest performance.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{DD} . . . . . 6 V
Input voltage, V_I . . . . . –0.3 V to V_{DD} +0.3 V
Continuous total power dissipation . . . . . internally limited (see Dissipation Rating Table)
Operating free-air temperature range, T_A . . . . . –40°C to 85°C
Operating junction temperature range, T_J . . . . . –40°C to 150°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$	DERATING FACTOR	$T_A = 70°C$	$T_A = 85°C$
PWP	2.7 W‡	21.8 mW/°C	1.7 W	1.4 W

‡ Please see the Texas Instruments document, *PowerPAD Thermally Enhanced Package Application Report* (literature number SLMA002), for more information on the PowerPAD package. The thermal data was measured on a PCB layout based on the information in the section entitled *Texas Instruments Recommended Board for PowerPAD* on page 33 of the before mentioned document.

recommended operating conditions

		MIN	MAX	UNIT
Supply voltage, V_{DD}		4.5	5.5	V
High-level input voltage, V_{IH}	SE/$\overline{\text{BTL}}$, HP/$\overline{\text{LINE}}$	4		V
	$\overline{\text{SHUTDOWN}}$	2		
Low-level input voltage, V_{IL}	SE/$\overline{\text{BTL}}$, HP/$\overline{\text{LINE}}$		3	V
	$\overline{\text{SHUTDOWN}}$		0.8	
Operating free-air temperature, T_A		–40	85	°C

electrical characteristics at specified free-air temperature, V_{DD} = 5 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$\lvert V_{OS}\rvert$	Output offset voltage (measured differentially)	V_I = 0, A_V = –2 V/V			25	mV
PSRR	Power supply rejection ratio	V_{DD} = 4.9 V to 5.1 V		77		dB
$\lvert I_{IH}\rvert$	High-level input current	V_{DD} = 5.5 V, $V_I = V_{DD}$			900	nA
$\lvert I_{IL}\rvert$	Low-level input current	V_{DD} = 5.5 V, V_I = 0 V			900	nA
I_{DD}	Supply current	BTL mode		18		mA
		SE mode		9		
$I_{DD(SD)}$	Supply current, shutdown mode			150	300	µA

operating characteristics, V_{DD} = 5 V, T_A = 25°C, R_L = 8 Ω, Gain = –2 V/V, BTL mode

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
P_O	Output power	THD = 1%, R_L = 4 Ω	f = 1 kHz,		1.9		W
THD + N	Total harmonic distortion plus noise	P_O = 1 W,	f = 20 Hz to 15 kHz		0.5%		
B_{OM}	Maximum output power bandwidth	THD = 5%			>15		kHz
	Supply ripple rejection ratio	f = 1 kHz, $C_{(BYP)}$ = 0.47 μF	BTL mode		68		dB
SNR	Signal-to-noise ratio				105		dB
V_n	Noise output voltage	$C_{(BYP)}$ = 0.47 μF, f = 20 Hz to 20 kHz	BTL mode		16		μV_{RMS}
			SE mode		30		
Z_i	Input impedance				See Table 1		

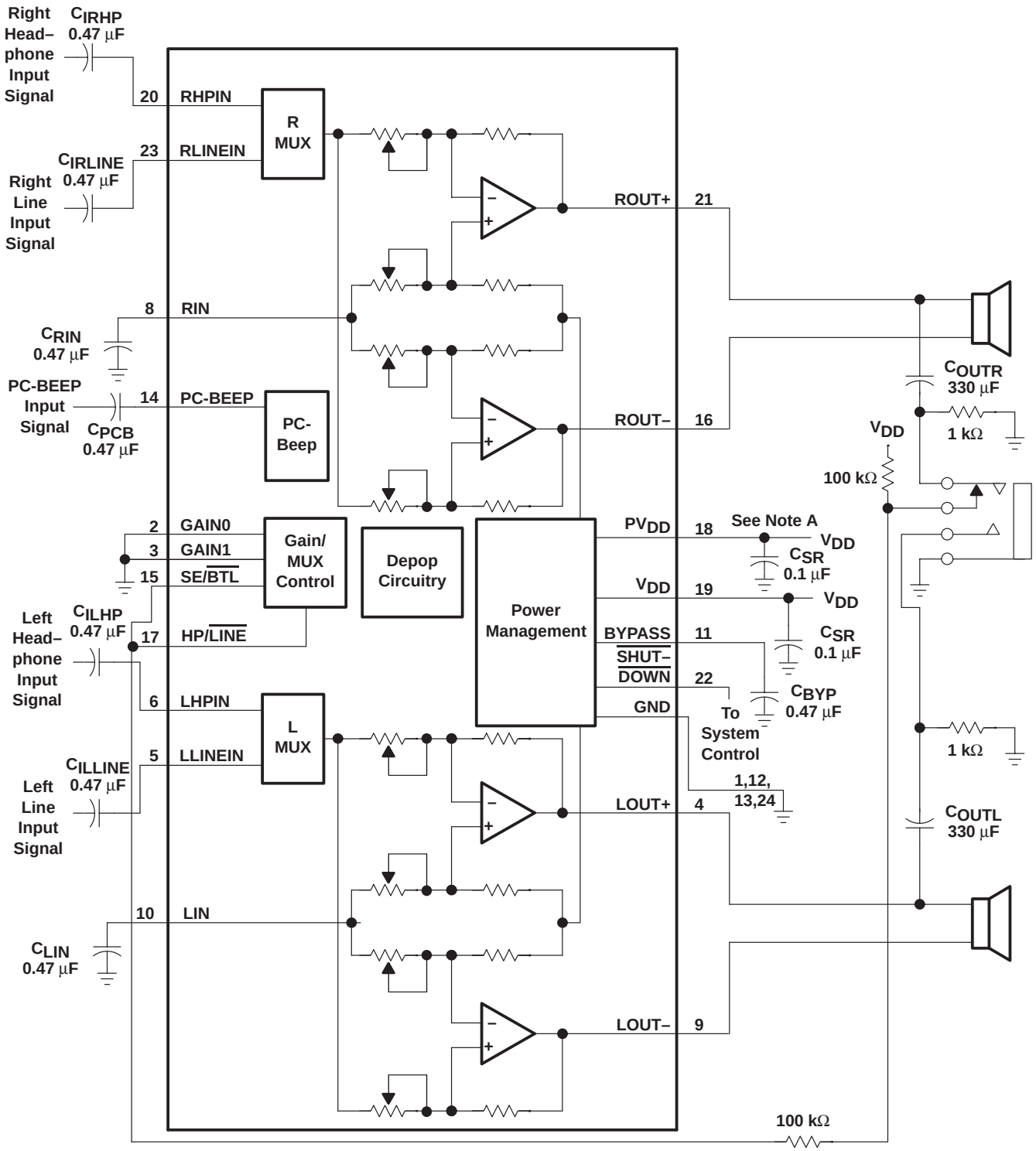
TYPICAL CHARACTERISTICS

Table of Graphs

			FIGURE
THD+N	Total harmonic distortion plus noise	vs Output power	1, 4–7, 10–13, 16–19, 21
		vs Frequency	2, 3, 8, 9, 14, 15, 20, 22
		vs Output voltage	23
V_n	Output noise voltage	vs Bandwidth	24
	Supply ripple rejection ratio	vs Frequency	25, 26
	Crosstalk	vs Frequency	27–29
	Shutdown attenuation	vs Frequency	30
SNR	Signal-to-noise ratio	vs Bandwidth	31
	Closed loop response		32–35
P_O	Output power	vs Load resistance	36, 37
P_D	Power dissipation	vs Output power	38, 39
		vs Ambient temperature	40

APPLICATION INFORMATION

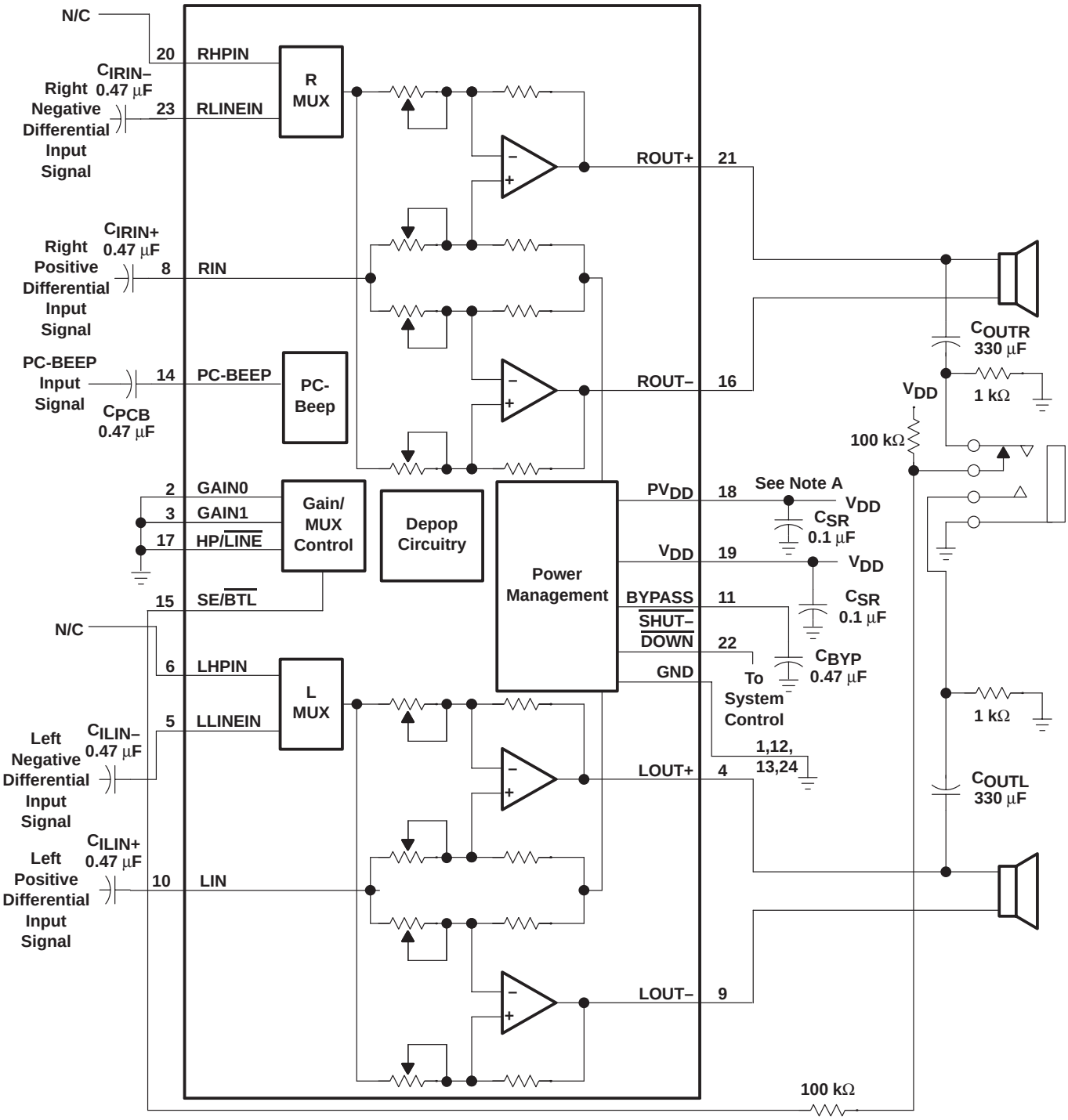
Figure 42 and Figure 43 are schematic diagrams of typical notebook computer application circuits.



NOTE A: A 0.1 µF ceramic capacitor should be placed as close as possible to the IC. For filtering lower–frequency noise signals, a larger electrolytic capacitor of 10 µF or greater should be placed near the audio power amplifier.

Figure 42. Typical TPA0222 Application Circuit Using Single-Ended Inputs and Input MUX

APPLICATION INFORMATION



NOTE A: A 0.1 µF ceramic capacitor should be placed as close as possible to the IC. For filtering lower–frequency noise signals, a larger electrolytic capacitor of 10 µF or greater should be placed near the audio power amplifier.

Figure 43. Typical TPA0222 Application Circuit Using Differential Inputs